

AMENDMENTS

This listing of claims will replace all prior versions and listings of claim in the application.

1. – 51. (Cancelled).

52. (Previously presented) A non-volatile memory system, comprising:

a card having a set of contacts on an external surface of said card, said card having a first surface and a second surface on an opposite side of said card from said first surface, said first surface having a raised portion;

a circuit board enclosed within said card;

a plurality of non-volatile storage elements enclosed within said card and connected to said circuit board; and

passive electrical elements enclosed within said card and connected to said circuit board, said passive electrical elements are positioned in a part of said card at least partially defined by said raised portion.

53. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said non-volatile storage elements are flash memory cells.

54. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said first surface defines a length and a width of said card.

55. (Previously presented) A non-volatile memory system according to claim 52, further comprising:

a controller element enclosed within said card and connected to said circuit board.

56. (Previously presented) A non-volatile memory system according to claim 55, wherein:

said passive electrical elements are in communication with said controller.

57. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said first surface is a top surface of said card.

58. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said passive electrical elements are capacitors.

59. (Previously presented) A non-volatile memory system according to claim 52, further comprising:

side surfaces between said first surface and said second surface.

60. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said raised portion provides a grip to grab said card.

61. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said card includes molding material encapsulating said circuit board, said non-volatile storage elements and said passive electrical elements.

62. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said non-volatile storage elements are flash memory devices in a flash memory array; and

said passive electrical elements are capacitors.

63. (Previously presented) A non-volatile memory system, comprising:
a card having a first dimension and a second dimension, said card has a first thickness along a first portion of said first dimensions and a second thickness along a second portion of said first dimension, said second thickness is greater than said first thickness;
a plurality of non-volatile storage elements enclosed within said card; and
passive electrical elements enclosed within said card, said passive electrical elements are positioned in said second portion.

64. (Previously presented) A non-volatile memory system according to claim 63, wherein:
said passive electrical elements are capacitors.

65. (Previously presented) A non-volatile memory system according to claim 64, wherein:
said first dimension is length;
said second dimension is width; and
said non-volatile storage elements are flash memory devices.

66. (Previously presented) A non-volatile memory system according to claim 63, wherein:
said first dimension is length; and
said second dimension is width.

67. (Previously presented) A non-volatile memory system according to claim 63, wherein:
said passive electrical elements are in electrical communication with said non-volatile storage elements.

68. (Previously presented) A non-volatile memory system according to claim 63, further comprising:

a circuit board, said non-volatile storage elements and said passive electrical elements are connected to said circuit board.

69. (Previously presented) A non-volatile memory system according to claim 68, further comprising:

a controller, said controller is positioned within said card and is in communication with said non-volatile storage elements; and

a set of electrical contacts on an external surface of said card, said set of electrical contacts are in communication with said controller.

70. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said non-volatile storage elements are flash memory devices.

71. (Previously presented) A non-volatile memory system according to claim 63, further comprising:

a controller element enclosed within said card and in communication with said non-volatile storage elements.

72. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said card having a first surface and a second surface on an opposite side of said card from said first surface, said first surface having a raised portion, said raised portion defines said second thickness.

73. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said card includes molding material encapsulating said plurality of non-volatile storage elements and said passive electrical elements.

74. – 79. (Cancelled)

80. (Previously presented) A non-volatile memory system, comprising:

a peripheral card having a first dimension and a second dimension, said card has a first thickness along a first portion of said first dimensions and a second thickness along a second portion of said first dimension, said second thickness is greater than said first thickness;

non-volatile storage elements enclosed within said peripheral card; and

a passive electrical component enclosed within said peripheral card, said passive electrical element is positioned in said second portion.

81. (Previously presented) A non-volatile memory system, comprising:

a peripheral card having a first surface and a second surface on an opposite side of said card from said first surface, said first surface having a raised portion;

a circuit board enclosed within said peripheral card;

a plurality of non-volatile storage elements enclosed within said peripheral card and connected to said circuit board; and

a passive electrical component enclosed within said peripheral card and connected to said circuit board, said passive electrical component is positioned in a part of said card at least partially defined by said raised portion.